

Title (en)

LIGHT MODULE ASSEMBLY HAVING REDUCED MOISTURE INGRESS AND METHOD FOR MANUFACTURING THE SAME

Title (de)

LICHTMODULANORDNUNG MIT REDUZIERTEM FEUCHTIGKEITSEINGANG UND VERFAHREN ZUR HERSTELLUNG DAVON

Title (fr)

ENSEMBLE MODULE DE LUMIÈRE AYANT UNE ENTRÉE D'HUMIDITÉ RÉDUITE ET SON PROCÉDÉ DE FABRICATION

Publication

EP 3234454 A1 20171025 (EN)

Application

EP 14908219 A 20141219

Priority

CN 2014094306 W 20141219

Abstract (en)

[origin: WO2016095184A1] A light module assembly (100) includes a lens (104), a circuit board (200), and an overmold body (102). The lens (104) includes one or more pooling structures (218, 220) formed by transversely oriented exterior surfaces (402, 404) of the lens (104). The circuit board (200) is coupled to the lens (104) and has one or more light-generating devices (106) disposed on the circuit board (200). The overmold body (102) is coupled to the lens (104) to form an interface (214) between the lens (104) and the overmold body (102). The interface (214) between the lens (104) and the overmold body (102) includes or defines moisture ingress path (216) into the circuit board (200). The one or more pooling structures (218, 220) prevent passage of moisture along the moisture ingress path (216) past the one or more pooling structures (218, 220) to the circuit board (200).

IPC 8 full level

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CPC (source: EP US)

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Designated extension state (EPC)

BA ME

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